Characterization of Edgeless Sensors

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Outline

- Motivation of edgeless detectors
- Introduction to edgeless sensors and Medipix chips
- Sensors under investigation
- > Measurement results:
 - I V characteristics
 - Dark field and flat field images
 - Object Images
 - Energy Calibration





Edgeless Detectors - Motivation

Drawback of conventional detectors against edgeless detectors

Miss of information in dead region problems for image reconstruction



Edgeless Sensors and Medipix chips

- Conventional sensors : Current Collection Ring (CCR) and Guard Rings (GR) in conventional sensors
- Edgeless sensors : Deep Reactive Ion Etching (DRIE), side implantation with Phosphorous or Borons, Aluminum Metallization, Passivation on top etc.

Ideal Edgeless Sensor:

- Good Quantum efficiency
- Low noise interprivation low leakage current and interprivation capacitance
- High breakdown voltage
- Small last pixel-to-edge distance
- Good sensitivity to low energy photons for edge pixels

Medipix family chips : Medipix1, Medipix2, Medipix3 and Medipix3RX



From LAMBDA to Edgeless LAMBDA

Edgeless detectors as part of LAMBDA ongoing FS-DS project



LAMBDA: Large Area Medipix Based Array

- Si sensor with 512 x 1536 (28 mm x 85 mm)
- 2 x 6 Medipix chips
- High-frame-rate readout system (2000 fps)

Silicon pixel sensor

Low Temperature Co-fired Ceramic (LTCC) board

High-speed IO

ASIC chip

Damaris

ASIC chip

- New future Developments: edgeless LAMBDA
 - Edgeless sensor compatible with Medipix chips
 - Medipix chips with TSV+RDL implemented
 - Ball Grid Array to board
 - <u>My task:</u> Characterization of edgeless sensors (without gard rings) coupled to conventional Medipix3 chips (without TSV + RDL)

Measured three different test structures







No Current Collection Ring

Current Collection Ring

Current Collection Ring

Polarity	n-on-p	Polarity	n-on-n	Polarity	n-on-p
Thickness	500 µm	Thickness	500 µm	Thickness	500 µm
Doping	1.1×10 ¹² cm ⁻³	Doping	7×10 ¹¹ cm ⁻³	Doping	1.1×10 ¹² cm ⁻³
V _{dep}	208.9 V	V _{dep}	132.9 V	V _{dep}	208.9 V
V _{breakdown}	22 V	V _{breakdown}	190 V	V _{breakdown}	35 V
V _{operation}	20 V	V _{operation}	160 V, 170 V, 180 V, 190 V	V _{operation}	20 V
W_{dep}	154,7 µm	W_{dep}	500 µm	W_{dep}	154,7 µm



I-V curves, Equalization



First and third sensor cannot depleted fully!



Dark and Flat Field Images for the three samples

Dark Field Image



Flat Field Image

V = 50kV l = 40mA



Second Sample

On increasing the applied voltage, the photons appear, but not all the pixels respond $\$



Problem during production? vendor (Advacam) confirmed: due to backside oxide layer not completely removed!!



Object Image and Flat Field Corrected Image

Raw Image of an Object (USB drive)



- Although the sensors are not fully depleted they can still work for imaging experiments
- Quality of the image after flat field correction gets better



Comparison Simulation and Experiment for first sample



- Edge pixels count differently from central pixels
- The results from the simulated normalized current reproduces the measurement results





Comparison Simulation and Experiment for first sample



 Prediction for a good sensor (full depletion) shows that the last few pixels counts much less than central pixels



Performance of Different Equalization Procedures

Equalized with X-rays shows a better performance



Results derived from the flat field image

Performance of Different Equalization Procedures

Equalized x-rays Equalized dark Image of an USB drive Image of an USB drive after flat field correction

Object Image for Equalized DAC with X-rays is slightly better than object image for Equalized dark Damaris | Characterization of Edgeless Sensors | September, 2014 | Page 14

DESY

Energy Spectrum



• Distortion in the energy spectrum due to charge summing



Energy Calibration



Summary

Three edgeless samples were tested:

- I-V measurement: the first and the third sample cannot be fully depleted!
- Flat field images with X-ray tube: Problem found for n⁺n sensor (production problem?)
- Object (USB drive) images taken: Both n⁺p sensors work, but it is a pity that 350 µm thick Si cannot be depleted! ☺
- Normalized counts (charge-collection) from edge pixels understood and compared to I-V simulation results:
 - Simulation shows good agreement to measurement
 - Prediction done for good sensors which can be fully depleted
- Different Equalization Procedures
 - Equalization performed with X-rays shows a slightly better performance
- Energy Spectrum
 - Distortion caused by charge summing



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Thanks for your attention!

